

IN THE CLAIMS

Claims 1-13 (canceled).

Claim 14 (New): A process for producing a hot plate wherein a resistance element having a thickness dispersion of $\pm 3 \mu\text{m}$ or less is formed on an insulating substrate, comprising forming said resistance element by a film-depositing method based on a dry process.

Claim 15 (New): A process for producing a hot plate wherein a resistance element having a thickness dispersion of $\pm 3 \mu\text{m}$ or less is formed on an insulating substrate, comprising forming said resistance element by RF sputtering.

Claim 16 (New): A process for producing a hot plate wherein a resistance element having a thickness dispersion of $\pm 3 \mu\text{m}$ or less is formed on an insulating substrate, comprising printing a resistance element paste made of scaly noble metal powder and firing the paste.

9. The hot plate according to any of claims 1 to 8,
characterized in that said resistance element is composed of
a titanium layer having a thickness of 0.1 to 0.5 μm , a molybdenum
layer having a thickness of 0.5 to 7.0 μm , on said titanium layer,
5 and a nickel layer having a thickness of 0.4 to 2.5 μm , on said
molybdenum layer.

10. (Cancelled)

10 11. (Cancelled)

12. (Cancelled)

13. (Added) The hot plate according to any of claims 1 to 9,
15 characterized in that said resistance element is formed on the
lower face of the insulating substrate.